



SCREEN's Sustainable Cost-of-Ownership (CoO) Portfolio for Wafer Inspection and Thickness Measurement Tools and experience on High Volume Manufacturing of Power and Automotive

Innovation for a Sustainable World

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SCREEN Semiconductor Solutions Co., Ltd.

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Cutting-edge Devices



SU-3400
Single Wafer Cleaner



SU-3300
Single Wafer Cleaner



SU-3200
Single Wafer Cleaner



SS-3300S
Spin Scrubber



RE-3500
Measurement System



SS-80EX
Spin Scrubber



SB-3300
Wafer Backside
Cleaning System



FC-3100
Wet Station



RF-300EX
Coat/Develop Track



RF-200EX
Coat/Develop Track

NEW



CW-2000
Compact Wet Station



VM-2500/3500
Measurement System



SC-80EX
Spray Coater



DT-3000
Coat/Develop Track



LA-3100
Flash Lamp Annealer



SP-2100
Spin Processor



SU-2000
Single Wafer Cleaner



ZI-3600
Inspection System



SK-60EX/SK-80EX
Coat/Develop Track

IoT Applications



SCREEN Automatic Microscopic Visual Inspection

ZI-3500 / ZI-3500 with BSI



Compact Design

Front Side Inspection

Microscopic automatic visual inspection
Selectable 3Lens

Backside - Backside Edge Inspection

Macro automatic visual inspection
Backside edge
Backside

Main features, options

- Automatic Defect Review (color images)
- Automatic Defects Classification
- Easy interface
- ADC / Screen AI Solution
- Various wafer handling capability
- CD/Overlay

ZI-3600 High Throughput



Compact Design

Front Side Inspection

Microscopic automatic visual inspection
Selectable 3Lens

Main features, options

- High throughput
- Automatic Defect Review (color images)
- Automatic Defects Classification
- Easy interface
- ADC / Screen AI Solution
- Various wafer handling capability
- CD/Overlay

SCREEN has launched SCRAIS as an AI approach.

- AI-based approaches to solve a range of problems:
 1. AI-based false defect filtering system
 - Already in use at several companies
 - Accelerate development to expand the scope of application
 2. Reduce labelling man-hours for AI model development
 - Developing methods to minimize labelling man-hours, which account for the majority of AI development man-hours
 3. Applying deep learning to ADC (Auto Defect Classification)
 - Under development for more accurate defect classification

Many other technologies in development...

SCREEN Film Thickness Measurement Tools

RE-3500

NEW



New Platform

SE mode : 2 times compared with old model

New Ellipsometry

Wavelength 230 nm - 800 nm with MSE

High accuracy and Repeatability

Film thickness Range: up to 1 μ m

Spectroscopic Reflectometer

Wavelength 400 nm - 800 nm: spot size : ϕ 10 μ m

Film thickness Range : 10 nm - 20 μ m

High Flexibility

Transfer the various Wafer size and Thin wafer without any modification

New Recipe creation support

VM-2500/3500



Compact Design

VM-2500 (200 mm)

VM-3500 (300 mm)

Spectroscopic Reflectometer

Standard Wavelength type: 400 nm - 800 nm

UV Wavelength type : 220 nm - 800 nm

IR Wavelength type : 400 nm - 1000 nm

Thickness Range

Standard Wavelength type: 10 nm - 20 μ m

UV Wavelength type : 2 nm - 20 μ m

IR Wavelength type : 10 nm - 120 μ m

High Throughput and Flexibility

Transfer the Small Wafer size and Thin wafer without any modification

New Recipe creation support

VM-3500-Trench



Compact Design

VM-3500 (200 mm)

Spectroscopic Reflectometer

Standard Wavelength type: 400 nm - 800 nm

UV Wavelength type : 220 nm - 800 nm

IR Wavelength type : 400 nm - 1000 nm

Trench depth measurement

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